

(19) World Intellectual Property Organization
International Bureau(43) International Publication Date
18 October 2007 (18.10.2007)

PCT

(10) International Publication Number
WO 2007/117030 A1

(51) International Patent Classification:

C08J 5/18 (2006.01) *B32B 15/08* (2006.01)
C08L 67/06 (2006.01) *G02F 1/1333* (2006.01)
C08L 67/07 (2006.01) *H05B 33/28* (2006.01)

(21) International Application Number:

PCT/JP2007/058019

(22) International Filing Date: 5 April 2007 (05.04.2007)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:

2006-105017 6 April 2006 (06.04.2006) JP

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

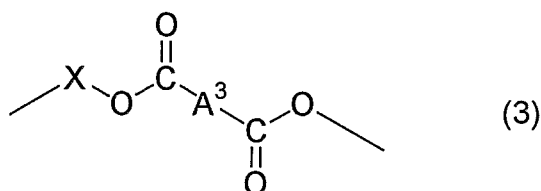
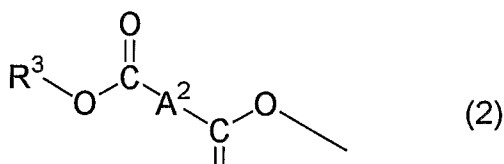
(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, MT, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— with international search report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: TRANSPARENT CONDUCTIVE SUBSTRATE



(57) Abstract: The invention provides a transparent conductive substrate using allyl ester heat-curable resin, comprising a compound having a group represented by formula (2) as terminus and a group represented by formula (3) as repeating unit, (In the formulae, R^3 , A^2 and A^3 have the same meanings as defined in the Description). The transparent conductive substrate is useful as a plastic substrate for display device, characterized by excellent heat resistance and chemical resistance, a low average linear expansion coefficient and high transparency, where warpage, deformation, crack of wiring are hard to occur in a process of thin film device formation.